

# Specification of Thermoelectric Module

## TEFC1-00823P

### Description

The 8 couples, 2.56 mm × 2.56/3.56mm size porch type module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 74 °C, designed for superior cooling and heating up to 100/200 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

### Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

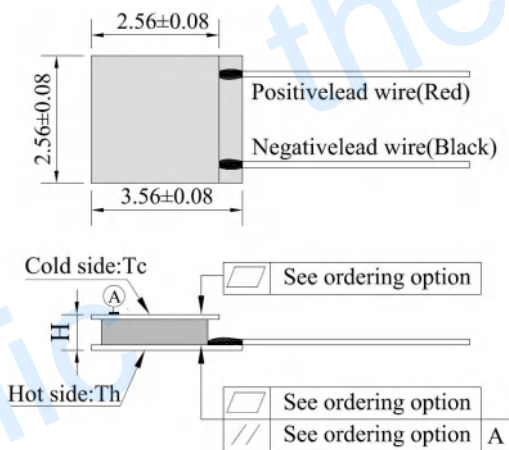
### Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

### Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>
DT <sub>max</sub> (°C)	74	83	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U <sub>max</sub> (Voltage)	1.05	1.13	Voltage applied to the module at DT <sub>max</sub>
I <sub>max</sub> (amps)	2.3	2.3	DC current through the modules at DT <sub>max</sub>
Q <sub>Cmax</sub> (Watts)	1.55	1.69	Cooling capacity at cold side of the module under DT=0 °C
AC resistance (ohms)	0.35	0.37	The module resistance is tested under AC
Tolerance (%)	10%		For thermal and electricity parameters

### Geometric Characteristics Dimensions in millimeters



### Manufacturing Options

#### A. Solder:

1. T100: BiSn (T<sub>melt</sub>=138°C)
2. T200: CuAgSn (T<sub>melt</sub> = 217°C)
3. T240: SbSn (T<sub>melt</sub> = 240°C)

#### B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant

#### C. Ceramics:

1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)
2. Aluminum Nitride (AlN)

#### D. Ceramics Surface Options:

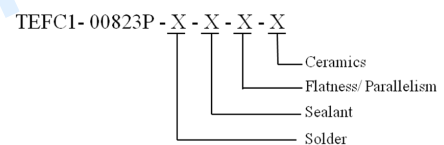
1. Blank ceramics (not metalized)
2. Metalized

### Ordering Option

Suffix	Thickness H (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0:0.97 ± 0.1	0: 0.03/0.03	20±3/Specify
TF	1:0.97±0.03	1: 0.015/0.015	20±3/Specify

Eg. TF01: Thickness 0.97 ± 0.1 (mm) and Flatness 0.015/0.015 (mm)

### Naming for the Module



TEFC1-00823P-T100-NS-TF01-AIO

T100: Solder, BiSn (Melting Point=138 °C)

NS: No sealing

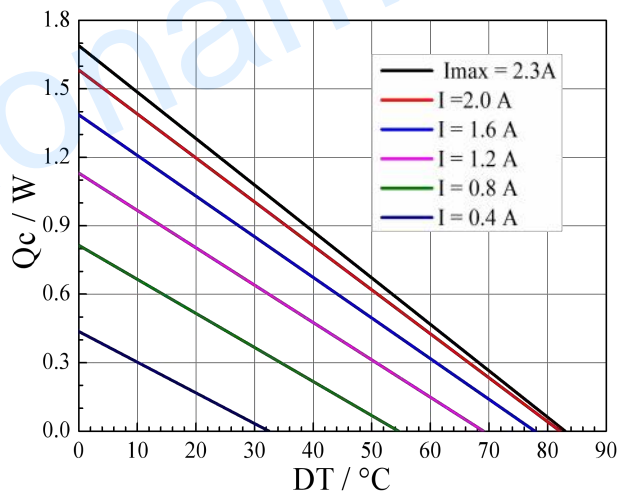
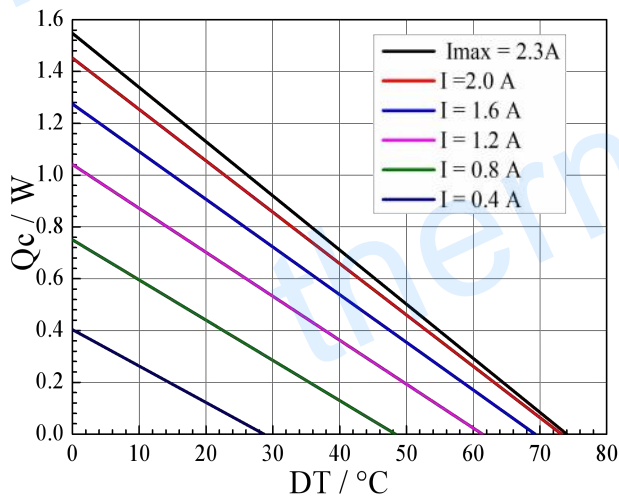
AIO: Alumina white 96%

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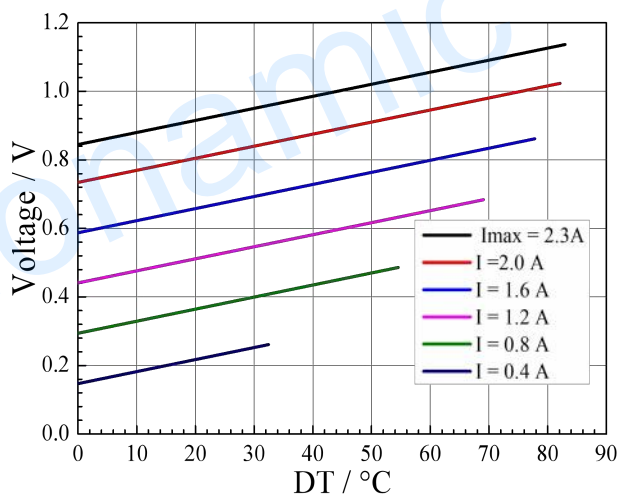
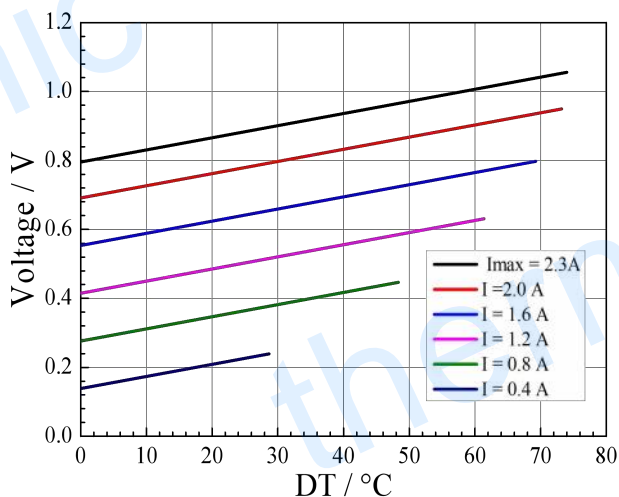
## TEFC1-00823P

### Performance Curves at Th=27 °C

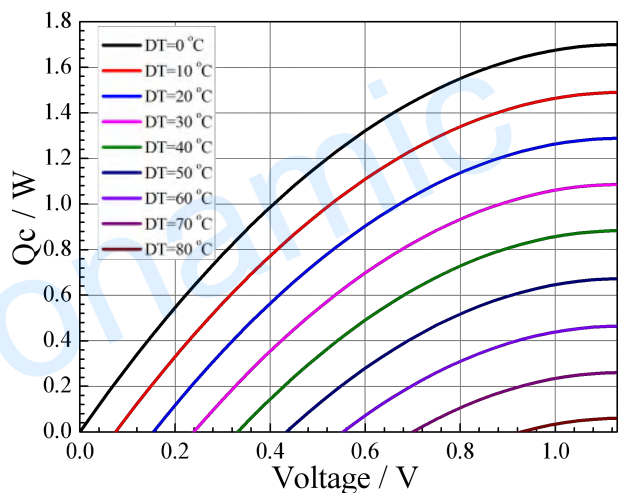
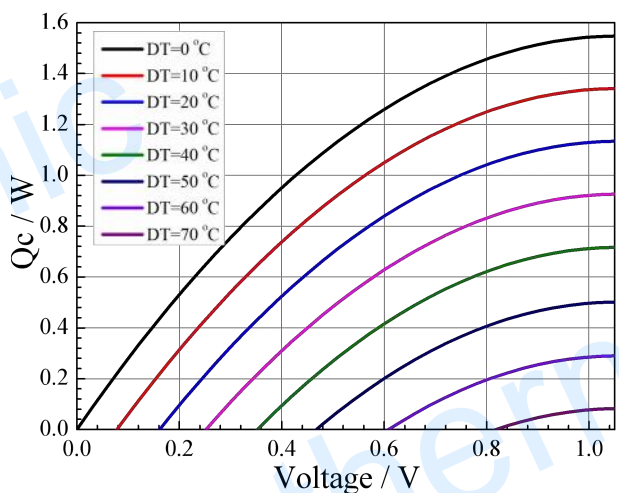
### Performance Curves at Th=50 °C



Standard Performance Graph  $Q_c = f(DT)$



Standard Performance Graph  $V = f(DT)$

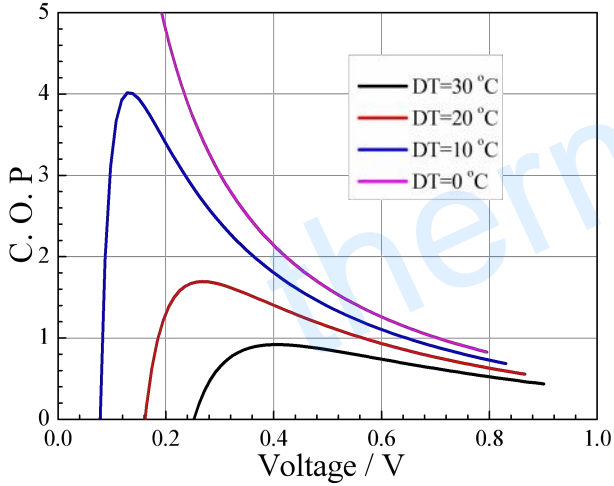


Standard Performance Graph  $Q_c = f(V)$

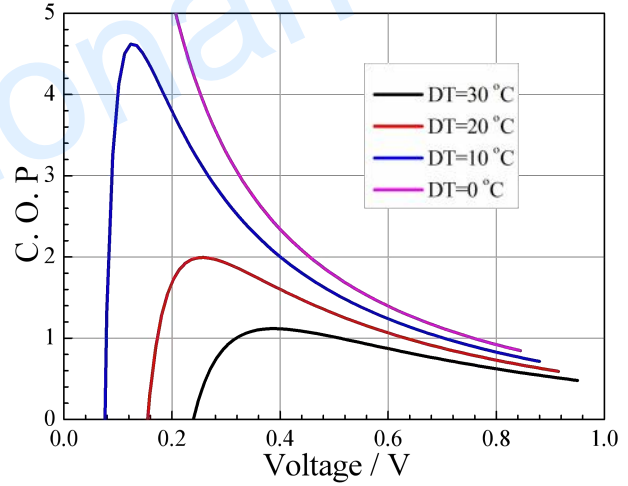
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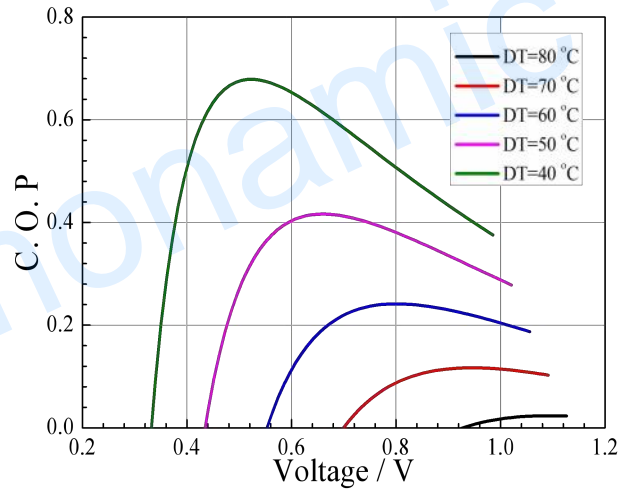
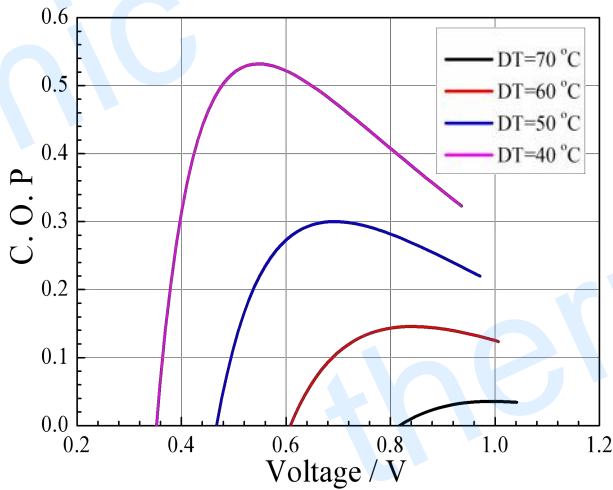
Performance Curves at  $T_h=27\text{ }^\circ\text{C}$



Performance Curves at  $T_h=50\text{ }^\circ\text{C}$



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of DT ranged from 40 to 70/80 °C

**Remark:** The coefficient of performance (COP) is the cooling power  $Q_c$ /Input power ( $V \times I$ ).

### Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below  $I_{max}$  or  $V_{max}$
- Work under DC

**Note:** All specifications subject to change without notice.